

**PRE-APPEAL BRIEF REQUEST FOR REVIEW**

Docket Number (Optional)

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on \_\_\_\_\_

Signature \_\_\_\_\_

Typed or printed name \_\_\_\_\_

Application Number

Filed

First Named Inventor

Art Unit

Examiner

Applicant requests review of the final rejection in the above-identified application. No amendments are being filed with this request.

This request is being filed with a notice of appeal.

The review is requested for the reason(s) stated on the attached sheet(s).

Note: No more than five (5) pages may be provided.

I am the

☐ applicant/inventor.

Signature

☐ assignee of record of the entire interest.  
See 37 CFR 3.71. Statement under 37 CFR 3.73(b) is enclosed.  
(Form PTO/SB/96)

Typed or printed name

☐ attorney or agent of record.

Registration number \_\_\_\_\_

Telephone number

☐ attorney or agent acting under 37 CFR 1.34.

Registration number if acting under 37 CFR 1.34 \_\_\_\_\_

Date

NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required.

Submit multiple forms if more than one signature is required, see below.

☐ \*Total of \_\_\_\_\_ forms are submitted.

This collection of information is required by 35 U.S.C. 132. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11, 1.14 and 41.6. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Applicant:** Daniel Watson

**Confirmation Number:** 7269

**Serial Number:** 10/783,933

**Examiner:** HENDRICKSON, Stuart L.

**Filed:** February 20, 2004

**Group Art Unit:** 1793

**Entitled:** THERMALLY TREATED  
POLYCRYSTALLINE DIAMOND (PCD)  
AND POLYCRYSTALLINE DIAMOND  
COMPACT (PDC) MATERIAL

**Attorney Docket Number:** 1157.008

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Alexandria, VA 22313-1450

**REASONS UPON WHICH REVIEW IS REQUESTED**

Applicant has filed a notice of appeal, and is requesting pre-appeal brief review. Applicant believes that the 35 USC §103(a) rejection of Claim 1 of the present application as unpatentable over *Lundin et al.* (5,103,701) taken with *Li et al.* (6,609,963) is improper. Applicant further believes that the 35 USC §103(a) rejection of Claim 1 as unpatentable over *Fang* (6,319,460) is improper. Applicant additionally believes that the 35 USC §102(b), or alternatively, §103(a) rejection of Claim 1 as anticipated or obvious over *Villela-Jirau* (6,030,596) is improper.

Applicant filed an amendment and response on January 21, 2008, to teach a toughened material that comprises a polycrystalline diamond material integrated with a second material, wherein the second material comprises a substantially continuous matrix in which granules of the polycrystalline diamond material are dispersed, and wherein the second material has a degree of ductility that is greater than that of the granules of the polycrystalline diamond material dispersed within the substantially continuous matrix.

Applicant's Claim 1 teaches a toughened material comprising a polycrystalline diamond material integrated with a second material, which can include iron, iron alloys, copper, copper alloys, a carbide, a ceramete, or combinations thereof. (Paragraph [00032]) The second material comprises a substantially continuous matrix in which granules of the polycrystalline diamond are dispersed, the second material having a degree of ductility greater than that of the granules of the polycrystalline diamond material. (Paragraph [00015])

The toughened material is formed by a process that includes subjecting the polycrystalline diamond material to multiple alternating cryogenic and heated tempering cycles, using specified target temperatures and controlled temperature rates of change. (Paragraph [0007])

The resulting toughened material has improved structural and material characteristics that include increased strength and toughness, and lowered brittleness. (Paragraphs [00027] and [0004]) The enhanced structural and material characteristics are obtained through use of the alternating cryogenic and heated tempering cycles, using temperatures and temperature rates of change that avoid over-stressing the polycrystalline diamond material or causing fractures. (Paragraphs [00021] and [00024])

*Lundin et al.* describe an apparatus for machining metals that detrimentally react with diamond cutting tools, in which the workpiece and diamond cutting tools are chilled to reduce wear on the diamond cutting tools. (*Lundin et al.*, Abstract)

*Lundin et al.* do not describe an unstressed toughened diamond material without fractures that possesses improved structural and material characteristics, which Applicant obtains by subjecting a polycrystalline diamond material integrated with a second material to alternating cryogenic and thermal tempering cycles.

*Lundin et al.* do not teach a second material having a substantially continuous matrix in which granules of the polycrystalline diamond material are dispersed, nor do *Lundin et al.* teach the second material having a degree of ductility greater than that of the granules of polycrystalline diamond material.

*Lundin et al.* teach only chilling a diamond tipped cutting tool and do not describe the components of the tool or improved structural characteristics resulting from the chilling.

*Li et al.* describe an abrasive tool that includes a superabrasive grain component, a filler component, and a vitreous bond component. (*Li*, Column 1, Lines 35-55) The abrasive tool is useable to grind polycrystalline diamond tools. (*Li*, Column 5, Lines 47-55)

*Li et al.* fail to teach an unstressed toughened diamond material without fractures that possesses improved structural and material characteristics, which Applicant obtains by subjecting a polycrystalline diamond material integrated with a second material to alternating cryogenic and thermal tempering cycles.

*Li et al.* also do not teach a second material having a substantially continuous matrix in which granules of the polycrystalline diamond material are dispersed, wherein the second material has a degree of ductility greater than that of the granules of polycrystalline diamond material.

*Fang* describes a super-hard composite material that includes a super-hard component and a metal matrix component, that has been compacted to an actual density of at least 95% of the theoretical maximum density of the mixture. (*Fang*, Column 2, Lines 48-57) *Fang* describes that materials such as diamond or cubic boron nitride are distributed in the metal matrix, and that the super-hard composite has a higher toughness and reduced wear resistance versus similar composites. (*Fang*, Column 3, Lines 9-16)

*Fang* fails to teach an unstressed toughened diamond material without fractures that possesses improved structural and material characteristics, obtained by subjecting a polycrystalline diamond material integrated with a second material to alternating cryogenic and thermal tempering cycles.

*Fang* instead teaches a diamond or cubic boron nitride – metal matrix compound that has high fracture toughness, achieved through compacting super-hard component with a metal matrix component. *Fang* does not teach the additional properties of decreased brittleness or a lack of fractures caused by stress from the creation process, which Applicant's toughened material exhibits due to the use of specified target temperatures and controlled temperature rates of change.

*Villea-Jirau* describes a method for synthesizing diamonds from carbon using copper as a solvent. (*Villea-Jirau*, Column 1, Lines 10-15) Under a pressure of up to

100,000 psi, while heating to 700-720 degrees Centigrade, the carbon crystallizes into the copper. (*Villea-Jirau*, Column 1, Lines 50-56 and Column 2, Lines 46-51)

*Villea-Jirau* fails to teach an unstressed toughened diamond material without fractures that possesses improved structural and material characteristics, which Applicant obtains by subjecting a polycrystalline diamond material integrated with a second material to alternating cryogenic and thermal tempering cycles. *Villea-Jirau* teaches only the synthesis of a diamond, using high pressure and a copper-based solvent.

Applicant's use of alternating cryogenic and thermal tempering cycles prevents stressing or fracturing of the diamond material, which can occur under high pressure, or through use of heating cycles alone. Further, Applicant's specified target temperatures and controlled temperature rates of change result in the formation of a toughened material with improved structural characteristics.

The art of record fails to teach a toughened material with improved structural characteristics, as taught by Applicant.

Applicant therefore believes that Claim 1 teaches past the art of record and is in condition for allowance, and such allowance is respectfully requested.

Reconsideration of this application in light of the above arguments is respectfully requested.

Respectfully submitted,



Wendy Buskop  
Reg. No. 32,202

Date: June 17, 2008

Please mail correspondence to:

The address associated with **CUSTOMER NO. 29637**

BUSKOP LAW GROUP, PC  
4511 DACOMA STREET  
HOUSTON, TEXAS 77092  
(TEL)713-403-7411  
(FAX)713-275-3419